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# Impact of Annealing Towards Anti-Reflection Properties of $Al_2O_3$ on Silicon

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## ABSTRACT

This paper investigates the impact of annealing towards the anti-reflection properties of aluminium oxide ($Al_2O_3$) on planar monocrystalline silicon (mono c-Si) wafers. $Al_2O_3$ anti-reflection coating (ARC) with 120 nm thickness is deposited on the c-Si wafers by radio frequency (RF) sputtering process at room temperature, with the power of 200 Watt and at a base pressure of $5\times10^{-5}$ mbar. This is followed by annealing at different temperatures (700-900 $^oC$) for 20 min. The results show that the root means square (RMS) surface roughness of the $Al_2O_3$ increases with increased annealing temperature. The $Al_2O_3$ films with annealing illustrate lower broadband reflection than the $Al_2O_3$ without annealing within the 300-1100 nm wavelength region. The $Al_2O_3$ film annealed at 900 $^oC$ exhibits the lowest reflection (6%) and the highest absorption (94%) at a wavelength of 600 nm with an average weighted reflection (AWR) of 20.4%, owing to the high RMS roughness and the effect of the intermediate refractive index of the $Al_2O_3$ layer. This results in a maximum potential short-circuit current density ($J_{sc(max)}$) of 37.3 mA/cm$^2$, which corresponds to a 5.4% enhancement compared to the $Al_2O_3$ on planar c-Si without an annealing process.

**Keywords:** *Annealing; antireflection; $Al_2O_3$; silicon*

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## INTRODUCTION

Crystalline silicon (c-Si) solar cells dominate over 90% of the worldwide photovoltaic (PV) market share due to improving conversion efficiency, reducing technology cost, technology maturity and proven stability [1, 2]. Since the c-Si in its original form exhibits high reflection (around 35-40% in the visible region) and poor light absorption, effective light management strategies are inevitable in the c-Si solar cells [3, 4]. In industrial monocrystalline (mono c-Si) solar cells, this is mitigated by incorporating microscale front pyramids on the c-Si surface, which scatter the incident light into oblique angles, resulting in lower broadband reflection and improved light absorption within 300-1100 nm wavelength region [5, 6]. Apart from that, a silicon nitride ($Si_3N_4$) anti-reflection coating (ARC) is deposited on the pyramids to further suppress the broadband reflection to below 3%, particularly near the wavelength of 600 nm, which represents the peak of AM1.5G solar spectrum [7, 8]. The reflection suppression is possible because the $SiN_x$ ARC has an optimum intermediate refractive index (n=2.0) to enable the quarter-wavelength AR effect [9, 10]. The suppressed reflection improves light-coupling into the c-Si, leading to increased broadband light absorption by the solar cells.

In the literature, various materials have been evaluated as ARC on c-Si solar cells, such as $Si_3N_4$, silicon dioxide ($SiO_2$) and aluminium oxide ($Al_2O_3$) [11, 12]. $Al_2O_3$ is a promising dielectric material with high transparency and refractive index n of 1.6 at a wavelength of 600 nm [13, 14]. Various techniques have been reported in the literature to deposit $Al_2O_3$, such as pulsed laser deposition, sputtering and atomic layer deposition (ALD) [14]. Recently, the fabrication of $Al_2O_3$/Si/$Al_2O_3$ by ALD (with 23 nm thickness) at different temperatures from 300 $^oC$ to 750 $^oC$ has been studied by Zhao et al. [15]. In another study by Singh et al. [13], $Al_2O_3$ ARC is deposited on p-type c-Si wafers by radio frequency (RF) sputtering, followed by annealing. As a result, the refractive index of the $Al_2O_3$ increases from 1.70 to 1.75 with increasing annealing temperature (350 to 600 $^oC$), and the local rearrangement of the atoms $Al_2O_3$ after annealing increases the coat density [13].

In this work, the impact of annealing towards the anti-reflection properties of $Al_2O_3$ ARC on c-Si is investigated. The $Al_2O_3$ ARC layers are deposited on planar c-Si wafers by RF sputtering. Then, the layers are subjected to different annealing temperatures. Surface morphological and optical properties of the $Al_2O_3$ layers are then characterised. The relationship between average weighted reflection (AWR) and different annealing temperatures is analysed. From the absorption curve, potential short-circuit current density ($J_{sc(max)}$) is used to estimate the light-coupling performance of the $Al_2O_3$ ARC layers within the 300-1100 nm wavelength region. From the possible results, $J_{sc(max)}$ enhancement is calculated for each sample. The results demonstrate the importance of the annealing process in reducing the broadband reflection and improving the potential $J_{sc(max)}$ that will be useful in c-Si solar cells.

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## EXPERIMENTAL

N-type (100) mono c-Si wafers with a thickness of 280 µm and resistivity of 5-10 Ω.cm are used in this experiment. Figure 1 illustrates the flow chart of the methodology used in this work. The c-Si wafers are cleaned by the Radio Corporation of America (RCA) technique to eliminate impurities such as organic residuals, metal contaminants and native oxide layer on the wafer surface [16]. After the RCA process, $Al_2O_3$ ARC with 120 nm thickness is deposited on the planar mono c-Si wafers by RF sputtering at room temperature, using RF power of 200 Watt and base pressure of $5\times10^{-5}$ mbar. The schematic of the $Al_2O_3$ ARC on the c-Si wafer is illustrated in Figure 2. After the sputtering process, the $Al_2O_3$ layer on planar c-Si wafers is annealed at different temperatures (700 °C, 800 °C and 900 °C) for 20 min in nitrogen ($N_2$) gas with a flow rate of 2 L/min.

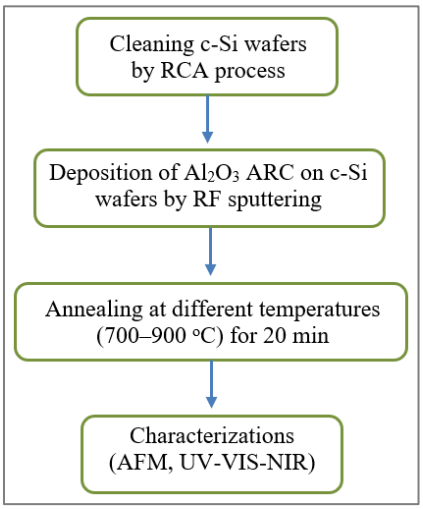



**Figure 1:** Flow chart of the methodology used in this work.

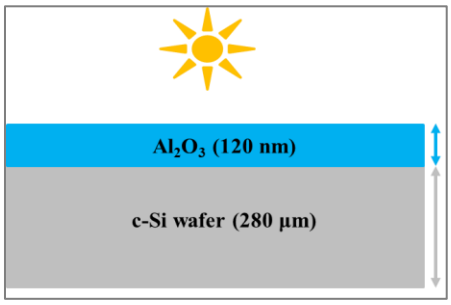



**Figure 2:** Schematic of $Al_2O_3$ ARC on the c-Si wafer. Note that the diagram is not to scale.

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For characterisations of the $Al_2O_3$ ARC surface morphological properties on c-Si wafers, atomic force microscopy (AFM) is used (model: Bruker Dimension Edge). AFM scan area of 10 μm × 10 μm and resolution of 512 data points are used to determine root means square (RMS) surface roughness. Optical properties of the $Al_2O_3$ are investigated by measuring the reflection (R) and transmission (T) using Agilent technologies Cary 5000 UV-Vis-NIR spectrophotometer (with integrating sphere). From the reflection profile, average weighted reflection (AWR) is calculated throughout the entire spectral region (300-1100 nm) using Equation (1) [17].

$$\mathrm{AWR}(\lambda) = \frac{\int_{\lambda=300nm}^{\lambda=1100nm} R(\lambda)S(\lambda)d\lambda}{\int_{\lambda=300nm}^{\lambda=1100nm} S(\lambda)d\lambda} \quad (1)$$

The reflection profile is then used to calculate absorption, using the relation: A = (100–R–T) % [18]. Transmission is equal to zero since the c-Si wafers are opaque. From the absorption result, the light-coupling performance of the $Al_2O_3$ ARC on c-Si is assessed using a concept of potential $J_{sc(max)}$. The potential $J_{sc(max)}$ is calculated by using Equation (2) for the 300-1100 nm wavelength region [19].

$$J_{sc(max)} = q\int_{\lambda=300nm}^{\lambda=1100nm} \mathrm{EQE}(\lambda).\mathrm{S}(\lambda)\mathrm{d}\lambda \quad (2)$$

where q represents the electron charge, λ is the wavelength of light, EQE is the external quantum efficiency (EQE=IQE×A), IQE is internal quantum efficiency (in this calculation, IQE=1), and S(λ) is the standard spectral photon density of AM1.5G solar spectrum.

## RESULTS AND DISCUSSION

### *Surface morphological properties*

Figure 3 (a)-(d) depicts AFM images of the $Al_2O_3$ on planar c-Si without annealing (i.e. as-deposited) and with different annealing temperatures (700-900 ºC). From the AFM images, it can be observed that the surface roughness of the $Al_2O_3$ surface increases with the increasing annealing temperature. The RMS roughness of 1.9 nm is obtained for the as-deposited layer. With annealing, the RMS roughness increases with increasing annealing temperature; 4.4 nm, 7.3 nm and 10.7 nm for annealing temperatures of 700 ºC, 800 ºC and 900 ºC, respectively. The increased RMS roughness corroborates well with the findings of Wang et al. [20] after annealing $Al_2O_3$ films deposited on c-Si wafers (using ALD) with temperatures of 400-900 ºC.

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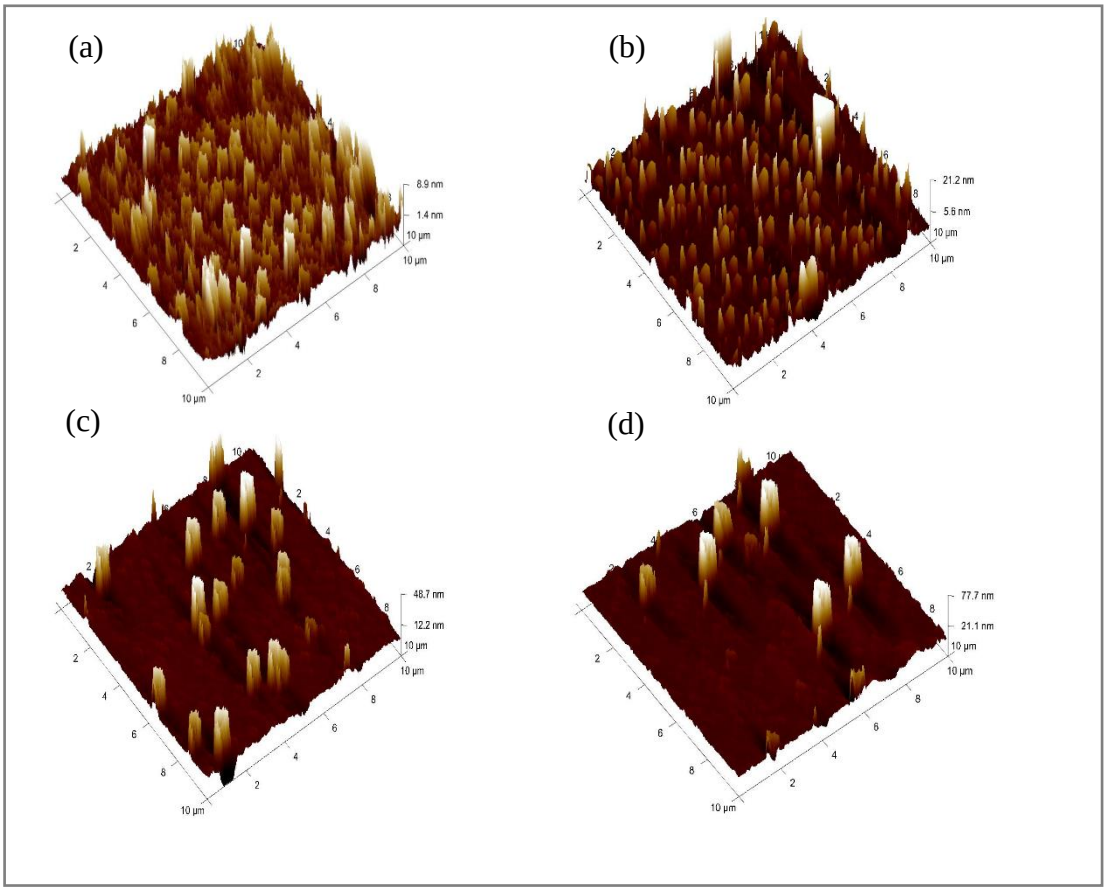



**Figure 3:** AFM images of $Al_2O_3$ on planar c-Si for (a) as-deposited (RMS roughness = 1.9 nm) and with annealing temperature of (b) 700 $^oC$ (RMS roughness = 4.4 nm), (c) 800 $^oC$ (RMS roughness = 7.3 nm) and (d) 900 $^oC$ (RMS roughness = 10.7 nm).

### *Optical properties*

Figures 4 (a) and (b) illustrate total reflection and absorption curves for $Al_2O_3$ ARC on planar c-Si wafers without annealing (as-deposited) and with different annealing temperatures within 300-1100 nm region. The total reflection and absorption curves for $Al_2O_3$ on planar c-Si without annealing are compared. The $Al_2O_3$ on planar c-Si without annealing illustrates a high reflection in the short wavelength region (350-800 nm). The reflection is 18.5% at a wavelength of 600 nm. The AWR of this sample is 22.3%. The reflection of the $Al_2O_3$ annealed at 700 $^oC$ falls to 13.3% at a wavelength of 600 nm (with AWR of 21.2%). This leads to absorption of around 86.7% at the same wavelength. With 800 $^oC$ annealing, the reflection reduces to 8% at 600 nm with AWR of 21%. This is attributed to enhanced light-coupling by the $Al_2O_3$ ARC on the c-Si at the higher annealing temperature. This leads to absorption of 92% at a wavelength of 600 nm.

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From Figure 4 (b), it can be observed that there is a decrease of absorption above 800 nm wavelength when the annealing temperature is increased to 800 ºC and 900 ºC. When annealed at 900 ºC, the reflection reduces to about 6% at 600 nm with an AWR of 20.4%. This is lower than 800 ºC, and the light absorption increases to 94% at the same wavelength.

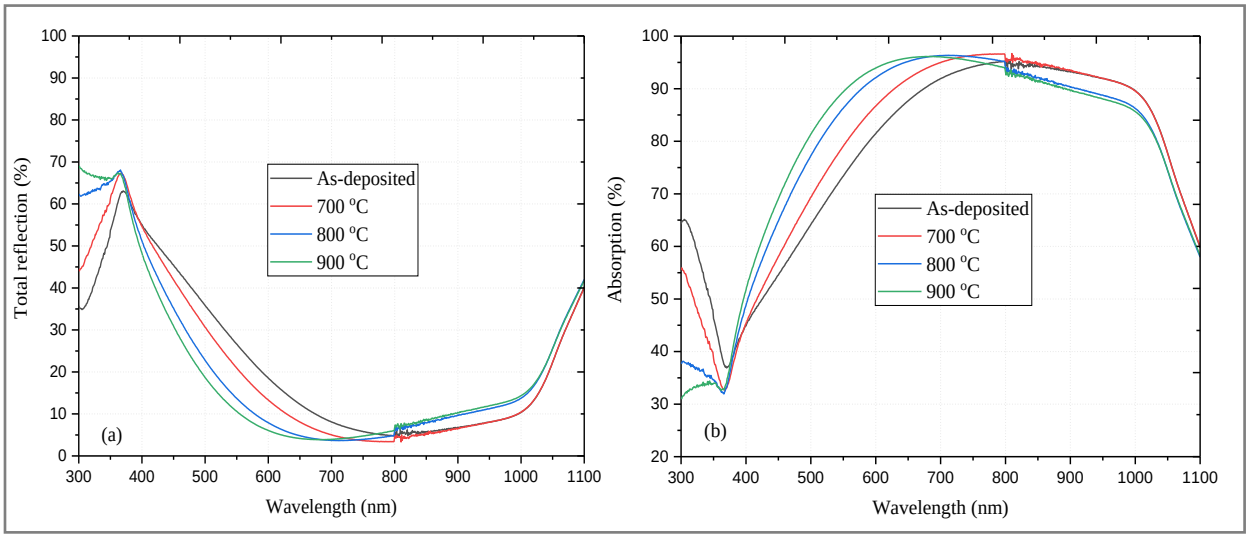



**Figure 4:** (a) Total reflection and (b) absorption curves of $Al_2O_3$ deposited on planar c-Si wafers, followed by annealing at different temperatures; 700 ºC, 800 ºC and 900 ºC. Note that as-deposited (without annealing) $Al_2O_3$ on planar c-Si is included for comparison.

Table 1 demonstrates the summary of AWR and potential $J_{sc(max)}$ of $Al_2O_3$ ARC on c-Si without annealing and with different annealing temperatures from 700 ºC to 900 ºC, as calculated by Equation (2). Note that potential $J_{sc(max)}$ enhancement (%) is calculated by normalising the improved potential $J_{sc(max)}$ of the sample over the potential $J_{sc(max)}$ of the $Al_2O_3$ on planar c-Si reference without annealing. The $Al_2O_3$ on planar c-Si without annealing temperature has AWR of 22.3% and potential $J_{sc(max)}$ of 35.4 mA/cm$^2$.

When the $Al_2O_3$ on planar c-Si annealed at 700 ºC, the AWR reduces to 21.2%, and the potential $J_{sc(max)}$ increases to 36.4 mA/cm$^2$ due to the lower light reflection in short wavelength (350-800 nm) region. This corresponds to a 2.8% enhancement compared to the $Al_2O_3$ without annealing and is attributed to the improved broadband light absorption by the $Al_2O_3$ roughness on the wafer surface. With 800 ºC annealing, the potential $J_{sc(max)}$ increases to 36.9 mA/cm$^2$. This is a 4.2% enhancement when compared to the $Al_2O_3$ without annealing. $Al_2O_3$ ARC annealed at 900 ºC demonstrates an increase of potential $J_{sc(max)}$ to 37.3 mA/cm$^2$ (or 5.4% enhancement) with AWR of 20.4% due to improved broadband light-coupling into the planar c-Si absorber. This is believed to be contributed by the highest RMS roughness (i.e. 10.7 nm) of the ARC layer on the c-Si wafer.

**Table 1:** Summary of AWR (within 300-1100 nm wavelength region), calculated potential $J_{sc(max)}$ and $J_{sc(max)}$ enhancement of $Al_2O_3$ on planar c-Si wafers with different annealing temperatures. The $J_{sc(max)}$

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enhancement (%) is calculated by normalising the improved potential $J_{sc(max)}$ of the $Al_2O_3$ on planar c-Si with annealing over the potential $J_{sc(max)}$ of the $Al_2O_3$ on planar c-Si without annealing (as-deposited)

| **Sample** | **AWR (%)** | **Potential $J_{sc(max)}$ (mA/cm$^2$)** | **Potential $J_{sc(max)}$ enhancement (%)** |
|---|---|---|---|
| As-deposited | 22.3 | 35.4 | - |
| 700 ºC | 21.2 | 36.4 | 2.8 |
| 800 ºC | 21.0 | 36.9 | 4.2 |
| 900 ºC | 20.4 | 37.3 | 5.4 |

## CONCLUSION

In this work, the impact of annealing towards the anti-reflection properties of $Al_2O_3$ on planar mono c-Si wafers is investigated. The $Al_2O_3$ ARC with 120 nm thickness is deposited on the c-Si wafers by RF sputtering. This is followed by annealing at different temperatures (700-900 ºC) for 20 min in $N_2$ ambient. From the AFM images, the surface of the $Al_2O_3$ on c-Si without annealing temperature is smooth, with an RMS surface roughness of 1.9 nm. The RMS roughness increases with increased annealing temperature. The RMS roughness for $Al_2O_3$ ARC on planar c-Si annealed at 700 ºC, 800 ºC and 900 ºC demonstrates illustrates an increasing trend; 4.4 nm, 7.3 nm and 10.7 nm, respectively. The $Al_2O_3$ ARC on planar c-Si without annealing exhibits reflection of 18.5% at a wavelength of 600 nm, with AWR of 22.3% and potential $J_{sc(max)}$ of 35.4 mA/cm$^2$. With annealing at 700 ºC, the reflection of the $Al_2O_3$ reduces to 13.3% at the same wavelength. This leads to AWR of 21.2% and absorption of around 86.7% at the same wavelength. With 800 ºC annealing, the reflection reduces to 8% at 600 nm with AWR of 21%. After annealing at 900 ºC, the reflection reduces to about 6% at 600 nm with an AWR of 20.4%. This is lower than the AWR of 800 ºC annealing and results in the highest absorption enhancement from 400 to 700 nm wavelength with potential $J_{sc(max)}$ of 37.3 mA/cm$^2$ due to the increase in the RMS surface roughness of the $Al_2O_3$ ARC on the planar c-Si substrate.

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## AUTHOR'S CONTRIBUTION

All the authors contributed to the study design, data analysis and writing of the manuscript.

## CONFLICT OF INTEREST STATEMENT

The authors agree that this research was conducted without any self-benefits or commercial or financial conflicts and declare the absence of conflicting interests with the funders.

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